Product / Package Information

Package	TQFP _EP
Body Size (mm)	14 X 14 X 1.0 (6.35 EP)
Lead Count	128
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.17E-01	86.91	869100	25.76	257644
Thermosets	Epoxy & Phenol resin	Proprietary	3.20E-02	12.78	127800	3.79	37886
Other inorganic materials	Carbon black	1333-86-4	7.75E-04	0.31	3100	0.09	919
Subtotal			2.50 E-01	100.00	1000000	29.64	296450

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.44E-01	96.20	962000	64.49	644925
Copper & its alloys	Nickel	7440-02-0	1.70E-02	3.00	30000	2.01	20112
Copper & its alloys	Silicon	7440-21-3	3.68E-03	0.65	6500	0.44	4358
Copper & its alloys	Magnesium	7439-95-4	8.48E-04	0.15	1500	0.10	1006
Subtotal			5.66 E-01	100.00	1000000	67.04	670400

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	0.000958406	9.58 E-04	100.0	1000000	0.11	1136

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	0.003422343	3.42 E-03	100.0	1000000	0.41	4056

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	5.20E-03	99.0	990000	0.62	6158
Precious Metals	Palladium	7440-05-3	5.25E-05	1.00	10000	0.01	62
Subtotal			5.25 E-03	100.00	1000000	0.62	6221

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.66 E-02	100.0	1000000	1.97	19707

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.26E-03	73.53	735300	0.15	1493
Other organic materials	Epoxy resin A	TS ref# 10013	1.26E-04	7.35	73500	0.01	149
Others	Anhydride	TS ref# 10181	1.26E-04	7.35	73500	0.01	149
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	5.04E-05	2.94	29400	0.01	60
Other organic materials	Epoxy resin B	TS ref# 10237	5.04E-05	2.94	29400	0.01	60
Others	Epoxy resin modifier	TS ref# 10038	5.04E-05	2.94	29400	0.01	60
Others	Anhydride	TS ref# 10180	5.04E-05	2.94	29400	0.01	60
Subtotal	Subtotal		1.71 E-03	99.99	999900	0.20	2030

	Weight (g)	Percentage (%)	PPM
Package Totals	**8.44 E-01**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES